

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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SANG MIN LEE	08/25/2023
JONG HYUN KANG	08/25/2023
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17562318
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DATE SIGNED:	09/07/2023
Total Attachments: 1 source=Executed_Assignment#page1.tif	

WORLD WIDE ASSIGNMENT

SSR 1/18

IN CONSIDERATION of good and valuable consideration provided to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

(Insert Name(s) & Address(es) of ASSIGNEE(S))

Samsung Electronics Co., Ltd.
 129, Samsung-ro, Yeongtong-gu,
 Suwon-si, Gyeonggi-do 16677
 Republic of Korea

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled
 (Title of Invention)

relating to International Patent Application PCT/KR2020/007383 and/or for which application for Letters Patent of the United States of America was executed on even date herewith or, if not so executed, was:

(a) executed on ; August 25, 2023 (Insert date of execution of application, if not concurrent)

(b) filed on , December 27, 2021

Serial No. 17/562,318

Any registered attorney or patent agent of STAAS & HALSEY LLP, 1201 New York Avenue, N.W., Suite 700 Washington, D.C. 20005 (202/434-1500) is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States of America and of any and all other countries granted on said invention and/or on said application and any rights of priority, extension, continuation, division, renewal, substitute, reissue, reviews (including inter partes review, post grant review and covered business method review), supplemental examination, interference, or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention in the United States of America and in any and all other countries, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), and in any rights of priority, extension, continuation, division, renewal, substitute, reissue, reviews, supplemental examination, interference, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be decided in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).
 (Typed Name & Signature of Inventor(s)) (Date) (Typed Name & Signature of Witness(es))

1) <u>Jun Su Jung</u> Jun Su JUNG	August 25, 2023	
2) <u>[Signature]</u> Sang Min LEE	August 25, 2023	
3) <u>[Signature]</u> Jong Hyun KANG	August 25, 2023	
4) _____		
5) _____		
6) _____		
7) _____		

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